#### Single Electron Interference and Diffraction Experiments with a High Energy Physics Detector

G.L. Alberghi<sup>(1,2)</sup>, S. Frabboni<sup>(3)</sup>, A. Gabrielli<sup>(1,2)</sup>, G.C. Gazzadi<sup>(3)</sup>
F. Giorgi<sup>(1)</sup>, G. Matteucci<sup>(2)</sup>, G. Pozzi<sup>(2)</sup>,
N. Semprini<sup>(1,2)</sup>, M. Villa<sup>(1,2)</sup>, A. Zoccoli<sup>(1,2)</sup>

- (1) Istituto Nazionale di Fisica Nucleare, Sez. Bologna
- (2) Physics Department Università di Bologna
- (3) CNR-Institute of Nanoscience-S3 and University of Modena and Reggio Emilia

# Outline

- Young's Experience
- Instrumentation:

Transmission Electronic Microscope Nanometric Double Slit Apsel 4D Sensor Data Acquisition System -> HW + FW + SW

- Preliminary Tests
- Single Electron Interference
- Conclusion

# Young's Experience

 $\lambda_{\text{De Broglie}} = h/p$ 

#### Basics

- Monochromatic/Monoenergetic coherent source



λ.

$$P(x) = |\psi_1 + \psi_2|^2 = |\psi_1|^2 + |\psi_2|^2 + 2\operatorname{Re}\psi_1^*\psi_2$$

R. Feynmann: - Lecture on Physics, Vol 3

Young's experiment with the electrons can only be conceptual in nature because of the smallness of the de **Broglie wavelength** 

### The Experimental Setup

- Instrumentation
  - Transmission Electron Microscope (TEM)
  - Nanometric Double Slit
  - APSEL 4D : High Space-Time Resolution Sensor
  - Data Acquisition System





#### The Microscope and the Setup

#### TEM Philips EM400T (120 keV max) 40 keV , v=0.4 c , λ=h/p= 5.9 pm

S

C

Ι

P

PO

S - Small size source

C - Sample with two slits

I,P - Image and projection lenses

PO: projection plane



5

Experimental conditions: plane wave approximation (Fraunhofer regime)

## The Double Slit



#### The Sensor : APSEL 4D

- Vertex detector for High Energy Physics
- ST 130nm CMOS Technology
- 4096 Monolithic Active Pixel Matrix
- Optimized for charged particle identification
- Each Pixel has Digital Output Hit / No Hit Position Time Stamp

x,y: spatial resolution 15 μm t: max time resolution 0.4 μs

Clock frequency: up to 20-50 MHz



Squared Pixels 50 x 50 µm Sensitive Area : 6.4 mm x 1.6 mm



### DAQ : Hardware

- Real Time Data Acquisition
- Sensor-> Board -> FPGA -> USB -> Computer
- Micrometric Bidimensional Movimentation



Chip-FPGA logic level conversion

### Hardware

Connections and Movimentation



#### Chip placement inside TEM



## The Programmable Board





- VHDL Code
  - Chip Configuration and Control
  - Data Reception, Elaboration, Formatting and Transmission to PC
  - Clock Management
    - Fast clock for Electronics
    - Slow control clock for Chip Configuration
    - Time Counter clock for the Sensor

#### Software

#### Graphic Interface for Chip control and Data Acquisiton

Controls and Configuratio	n Configuration Pixel Matrix	Monitoring
Input Configuration		Write
Output Directory		Read
Current Status		Button 3
State Machine	DAQ Monitoring	
Config Xilinx	FSM Status:	
Config APSEL	Hit Rate :	
Start DAQ	Storage Rate (kb/s) :	
Start Storing	Commento Pre	Commento Post
Stop Storing		
Stop DAQ		

- C++ code
- Qt widget-based graphical libraries
- Qwt libraries for graphical visualization of events and histograms

```
← Standard user interface
```

#### Software

#### Single Registers

#### Pixel Configuration Interface

Controls and Configuration	Configuration	Pixel Matrix	Monitoring	Debug RW	Debug RO	monitor online Gigiqwt	Time Rate Histogram Gigiqwt	Pres
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RW (2): ConfigReg				Hex	Hex	Read	Write	6
RW (3) : BCODelays				Hex	Hex	Read	Write	5
RW (4) : DACRegister				Hex	Hex	Read	Write	3
RW (5) : ApselCommnd				Hex	Hex	Read	Write	1
RW (6) : DataToAPSEL[0]				Hex	Hex	Read	Write	0
RW (7) : DataToAPSEL[1]				Hex	Hex	Read	Write	Disabled
RW (8) : SC_dk_div				Hex	Hex	Read	Write	Rows
RW (9) : BC_offset				Hex	Hex	Read	Write	
RW (10) : BCOHalfPeriod Per BCO clock Manager				Hex	Hex	Read	Write	P
RW (11) : Config Hit Gen Per hit generator				Hex	Hex	Read	Write	P
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Pix 2	T		Ptx	6	T	Ptx	10		Pix 14		Pα 1	8			
Pix 3	T		Pix	7		Pix	11		οiα 15		Pix 1	9	1		rixeis
			Pix	8	70	Pix	12		Pix 16		Pix 2	0			

## Setup Test : Imaging

Images of Single and Triple Slit on the sensor



Single Slit

#### **Triple Slit**



**32 x 128 Pixel Matrix** <sup>15</sup>

32 x 128 Pixel Matrix

#### **Carbon Grating Diffraction**

Carbon diffraction grating: typical pitch 400 nm 40-60 keV electrons:  $\lambda = h/p = 5-6$  pm, typical angle 10<sup>-5</sup> rad Observation windows: 165 µs (6k fps)



## **Carbon Grating Diffraction**



Very High Statistic ~ 10 Million Hits



#### Single-electron interference I

Double slit: distance d = 440 nm 40 keV electrons:  $\lambda = h/p = 5.9 \text{ pm}$ Observation windows : 165 µs (6k fps)



#### Single-electron interference II

Double slit: distance d=440 nm 40 keV electrons:  $\lambda = h/p = 5.9 \text{ pm}$ Observation windows 165 µs (6k fps) Add Frames



Statistica accumulata: 500

#### Single-electron interference III



### Conclusion

- We used for the first time a system of nanometric-slits with a high space-time performance sensor
- APSEL 4D (4096 pixels, 6k fps→2M fps) developed by INFN via a R&D project oriented to the next generation of silicon trackers (SLIM5).
- Developed a custom Hardware-Firmware-Software full DAQ chain
- **Reconstructed** the Young interference with single electrons
- The DAQ chain can be used for Chip and Electronics Characterization
- The time resolution characteristics can be used in a new field of electron microscopy: the study of dynamic phenomena.



# Deep NWell MAPS design

- CMOS MAPS for future vertex detectors: thin (OK!) but also need to be fast (i.e. bkgd rate @ SuperB: several MHz/cm2)
- New approach: hybrid-pixel-like structure to improve the readout speed
- <u>Full in-pixel signal processing chain</u> exploiting triple well CMOS process
  - Deep NWell as collecting electrode with most of the front-end overalapped in the pwell
  - Can extend collecting electrode (charge preamp --> gain independent of sensor cap.)
  - Allow design with small <u>"competitive"</u> <u>nwells</u> for PMOS inside the pixel. Area kept to a minimum:, they steel signal to the main DNW electrode.
  - Fill factor = DNW/total n-well area
     ~90% in present design



# MAPS efficiency vs position within pixel



Correspondence between the pixel layout and the efficiency map.

Efficiency map inside pixel cell. Cross feed unfolded results.

# Instrumentation

- TEM Philips M400T (120 keV max)
- Two nanometric slits
- slit width 95 nm
- Slit length 1550 nm
- Slit distance 440 nm
- 4096 MAPs Sensor
   ST 130nm CMOS \_\_\_\_\_

DAQ system





# Set-up inside the TEM

S- Sma C - Sar C I,P - In pr I PO: pro P Experi

PO

- S- Small size source
- C Sample with two slits
- I,P Image and projection lenses
- PO: projection plane
- P Experimental conditions:
   Fraunhofer regime
   (plane wave
   approximation)



## Set-up nel Microscopio



- S- Sorgente di piccole dimensioni Elettroni da 40 keV , v=0.4 c  $\lambda$ =h/p= 5.9 pm (1/18 diametro H),
- C Campione a due fenditure distanza d=440 nm
- I, P Lenti immagine e di proiezione
- PO: piano di proiezione delle fenditure

Condizioni sperimentali: Regime di Fraunhofer (approssimazione di onde piane)

# APSEL 4D Sensor

Sviluppato dalla Collaborazione SLIM5 per un progetto per esperimenti di fisica delle particelle-> Rivelatore di vertice di SuperB (INFN: BG, BO, PI, PV, TS)

Sensore Monolitico a Pixel Attivi Tecnologia CMOS ST 130 nm

Architettura di readout integrata, ottimizzata per il tracciamento di particelle cariche

Informazione di uscita 3D: x,y: risoluzione spaziale 15 μm t: risoluzione temporale > 0.4 μs

Frequenza di clock: 20-50 MHz



#### Pixels quadrati di lato 50 $\mu$ m Area sensibile: 6.4 mm x 1.6 mm = 10 mm<sup>2</sup>



## Data Acquisition

- Real Time Data Acquisition
- Sensor-> FPGA -> USB -> Computer
- Micrometric Bidimensional Movimentation



#### Pixel Configuration Interface

						м	acro	Pix	el M	latri	x							
	31-	28	27-24		23-20		19-16		15-12	2	11-0	1	7-4		0-3			
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Ptx 2	1	11	Ptx 6			Ptx 10			Pix 1	4		Pr	× 19	11	Si	nal	e Pi	xels
Pix 3	-	] [	Pix 7			Pix 11			Pix 1	5		Pi	× 19					
Pix 4	-		Pix 8			Pix 12			Pbt 1	6		Pi	× 20					

#### Thin wire Diffraction

40-60 keV electrons:  $\lambda = h/p = 5,9 \text{ pm}$ , typical angle  $10^{-5}$  rad Average Hits per frame ~ 1 -> Single Electron



#### Calibration : Carbon Grating Diffraction

Carbon Grating Diffraction: typical step 400 nm 40 keV Electrons :  $\lambda$ =h/p= 5,9 pm, angles  $\approx$  10<sup>-5</sup> rad

3 millisecond observation windows



## The single-electron interference III



## The single-electron interference IV

